

AMENDMENT TRANSMITTAL LETTER

Docket No. M4065.0319/P319

Application No.	Filing Date	Examiner	Art Unit
09/296,835	April 22, 1999	Erik Kielin	2813

Applicant(s): Ronald A. Weimer, et al.

FABRICATION OF DRAM AND OTHER SEMICONDUCTOR DEVICES WITH AN INSULATING FILM USING A WET RAPID THERMAL OXIDATION PROCESS

TO THE COMMISSIONER FOR PATENTS

Transmitted herewith is an amendment in the above-identified application.

		CLAIM	S AS AMENI	DED	
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	
Total Claims	14	- 40 =		x	0.00
ndependent Claims	7	- 8 =		X	0.00
Multiple Depen	dent Claims (ch	eck if applicabl	(e)		
Other fee (plea	se specify):				
TOTAL ADDIT	TIONAL FEE FO	OR THIS AME	NDMENT:	4.0	
x Large Entity	/			Small Er	ntity
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Payment by	credit card. Fo	orm PTO-2038	is attached.		
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x Credit a	any overpaymer	nt.			
x Charge	any additional fil	ing or applicatio	on processing t	ees required und	der 37 CFR 1.16 and 1.17.
	mo			Dated: _	November 12, 2002
Thomas J. D'A Attorney Reg.				Dated: _	November 12, 2002

2002



Docket No.: M4065.0319/P319 (PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Ronald A. Weimer, et al.

Application No.: 09/296,835

Group Art Unit: 2813

Filed: April 22, 1999

Examiner: Erik Kielin

For: FABRICATION OF DRAM AND OTHER

SEMICONDUCTOR DEVICES WITH AN

INSULATING FILM USING A WET

RAPID THERMAL OXIDATION PROCESS

AMENDMENT

BOX: Non-Fee Amendment Commissioner for Patents Washington, DC 20231

Dear Sir:

This paper is responsive to the Office Action dated August 12, 2002, rejecting claims 2-5, 8, 10-12, and 42-44. Please amend the above-captioned U.S. Patent application as follows:

IN THE CLAIMS:

Please replace claims with 8 and 42-44 with amended claims 8 and 42-44 below.

8. (five times amended) A method of fabricating a semiconductor device

comprising:

depositing an oxygen-deficient dielectric film having a dielectric constant of at at 25 over an underlying layer;

least about 25 over an underlying layer;

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